CHISIC 2025 Full Program					
CICC - CHISIC Joint Session			*Wed, Apr 16th, 2025*		
13:30	14:20	Invited Paper	*Packaging Technologies*		TSMC
14:20	15:10	Invited Paper	*A high-performance Passive Base System for distributed AI/Media acceleration*		Intel
15:10	15:35		*Break*		
15:35	16:00	Regular Paper	*A 68 TOPS/W, 256MB SRAM Sparse GEMM Accelerator Tiled Across 16, 4nm Near Memory Compute (NMC) Chiplets Disaggregated 2.5D System*		Intel
16:00	16:50	Invited Paper	*3D-IC Chiplet Integrated Power Supply with LDO, SCVR, and Buck DC-DC Converter*		Tsinghua University
16:50	17:15	Regular Paper	*On-Chip Circuit Harness Enabling Probe-Less, Position-Invariant and Massive Testing of Chiplets via Die Front/Back-Side Capacitive Coupling*		National University of Singapore
17:15	17:30		*Break*		
17:30	18:15	CHISIC Keynote	*Chip to Chip Communication for Next Generation AI Datacenters*	Tom Gray	Nvidia
18:15	20:15		*CHISIC Networking Reception*		
CHISIC			*Thu, Apr 17th, 2025*		
7:00	8:00		*Breakfast*		
8:00	8:45	CHISIC Keynote	*Petascale photonic connectivity for energy efficient computing*	Keren Bergman	Columbia University
8:45	9:25	Invited Talk	*Chiplets and Connectivity Driving Next-Gen AI Networks*	ony Chan Carusor	University of Toronto
9:25	10:05	Invited Talk	*Power-Efficient Short Reach Electrical Links for the AI Era*	Tod Dickson	IBM
10:05	10:20		*Coffee Break*		
10:20	11:00	Invited Talk	*Open Chiplet Platforms for Embodied AI*	Luca Benini	ETH/UniBO
11:00	11:40	Invited Talk	*Architecting Heterogenous System-of-Chiplets for Data Center and AI Era*	Surhud Khare	Intel
11:40	12:20	Invited Talk	*Building Composable Chiplets*	Andreas Olofsson	ZeroASIC
12:20	12:25		*Group Pictures*		
12:25	13:25		*Lunch Break*		
13:25	14:05	Invited Talk	*Enabling AI revolution through innovations in advanced packaging and chiplet technology*	Deepak Kulkarni	AMD
14:05	14:45	Invited Talk	*STCO, a new design paradigm to meet the challenges in designing 3D IC designs*	Tony Mastroianni	Siemens
14:45	15:25	Invited Talk	*EDA Solutions for Chiplet-based Multi-Die Systems*	Henry Sheng	Synopsys
15:25	15:40		*Coffee Break*		
15:40	16:20	Invited Talk	*Navigating the Cooling Conundrum: A Thermal Roadmap for AI Modules*	Yin Hang	Meta
16:20	17:00	Invited Talk	*Reliability and Test of System-of-Chiplets in the AI Era*	Mehul Shroff	NXP
17:00	17:05		*Closing ceremony*		